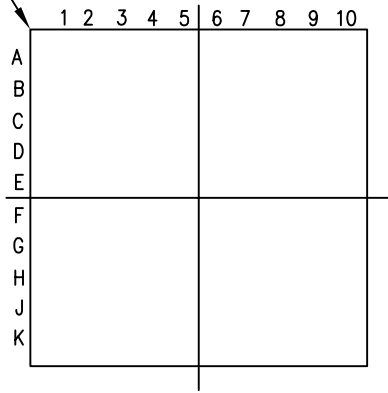
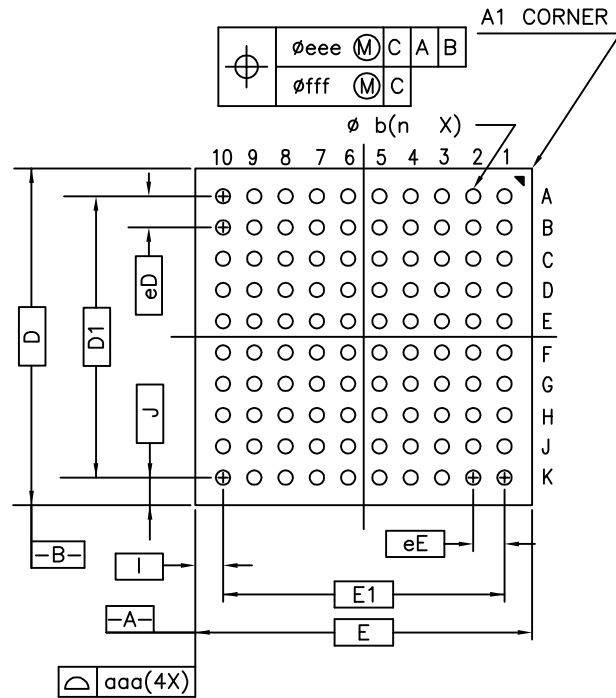


TOP VIEW

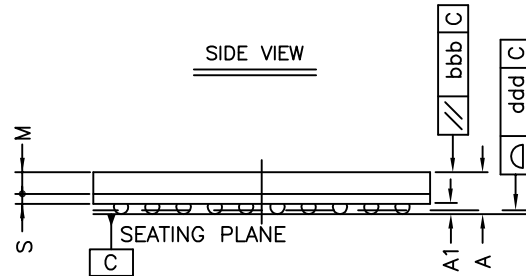
PIN A1 CORNER



BOTTOM VIEW



SIDE VIEW



		Symbol	Common Dimensions
Package :			VFPGA
Body Size:	X	E	7.000±0.100
	Y	D	7.000±0.100
Ball Pitch :	X	eE	0.650
	Y	eD	0.650
Total Thickness :		A	1.000 MAX
Mold Thickness :		M	0.450 Ref.
Substrate Thickness :		S	0.210 Ref.
Ball Diameter :			0.300
Stand Off :		A1	0.160 ~ 0.260
Ball Width :		b	0.270 ~ 0.370
Package Edge Tolerance :		aaa	0.100
Mold Flatness :		bbb	0.100
Coplanarity:		ddd	0.080
Ball Offset (Package) :		eee	0.150
Ball Offset (Ball) :		fff	0.080
Ball Count :		n	100
Edge Ball Center to Center :	X	E1	5.850
	Y	D1	5.850
Corner Ball Center to Package Edge:	X	I	0.575
	Y	J	0.575